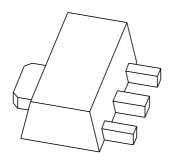
# DISCRETE SEMICONDUCTORS

# DATA SHEET



# **BZV49 series**Voltage regulator diodes

Product data sheet Supersedes data of 1999 May 11 2005 Feb 03



# Voltage regulator diodes

#### **BZV49** series

#### **FEATURES**

• Total power dissipation: max. 1 W

• Tolerance series: approx. ±5%

• Working voltage range: nom. 2.4 to 75 V (E24 range)

 Non-repetitive peak reverse power dissipation: max, 40 W.

#### **APPLICATIONS**

· General regulation functions.

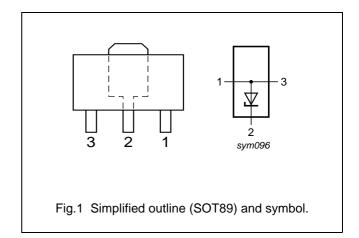
#### **DESCRIPTION**

Medium-power voltage regulator diodes in a SOT89 plastic SMD package.

The diodes are available in the normalized E24 approx.  $\pm 5\%$  tolerance range. The series consists of 37 types with nominal working voltages from 2.4 to 75 V (BZV49-C2V4 to BZV49-C75).

#### **PINNING**

PIN	DESCRIPTION
1	anode
2	cathode
3	anode



#### **ORDERING INFORMATION**

TYPE NUMBER	PACKAGE							
TIPE NOWIBER	NAME	DESCRIPTION	VERSION					
BZV49-C2V4 to BZV49-C75 note 1	SC-62	plastic surface mounted package; collector pad for good heat transfer; 3 leads	SOT89					

#### Note

1. The series consists of 37 types with nominal working voltages from 2.4 to 75 V (E24 range).

#### **MARKING**

TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE
BZV49-C2V4	2Y4	BZV49-C6V2	6Y2	BZV49-C16	16Y	BZV49-C43	43Y
BZV49-C2V7	2Y7	BZV49-C6V8	6Y8	BZV49-C18	18Y	BZV49-C47	47Y
BZV49-C3V0	3Y0	BZV49-C7V5	7Y5	BZV49-C20	20Y	BZV49-C51	51Y
BZV49-C3Y3	3Y3	BZV49-C8V2	8Y2	BZV49-C22	22Y	BZV49-C56	56Y
BZV49-C3V6	3Y6	BZV49-C9V1	9Y1	BZV49-C24	24Y	BZV49-C62	62Y
BZV49-C3V9	3Y9	BZV49-C10	10Y	BZV49-C27	27Y	BZV49-C68	68Y
BZV49-C4V3	4Y3	BZV49-C11	11Y	BZV49-C30	30Y	BZV49-C75	75Y
BZV49-C4V7	4Y7	BZV49-C12	12Y	BZV49-C33	33Y	_	-
BZV49-C5V1	5Y1	BZV49-C13	13Y	BZV49-C36	36Y	_	_
BZV49-C5V6	5Y6	BZV49-C15	15Y	BZV49-C39	39Y	-	-

# Voltage regulator diodes

BZV49 series

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	PARAMETER CONDITIONS			
I <sub>F</sub>	continuous forward current		_	250	mA
I <sub>ZSM</sub>	non-repetitive peak reverse current	$t_p$ = 100 μs; square wave; $T_j$ = 25 °C prior to surge	see Table "Per type		
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C; note 1	_	1	W
P <sub>ZSM</sub>	non-repetitive peak reverse power dissipation	$t_p$ = 100 μs; square wave; $T_j$ = 25 °C prior to surge; see Fig.2	_	40	W
T <sub>stg</sub>	storage temperature		-65	+150	°C
T <sub>i</sub>	junction temperature		_	150	°C

#### Note

1. Device mounted on a ceramic substrate; area =  $2.5 \text{ cm}^2$ ; thickness = 0.7 mm.

#### **ELECTRICAL CHARACTERISTICS**

#### **Total series**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 50 mA; see Fig.3	1	V

BZV49 series

Per type  $T_j = 25$  °C unless otherwise specified.

BZV49- CXXX	VOLT V <sub>Z</sub>	OLTAGE RESIST $V_Z(V)$ $r_{dif}(V)$		DIFFERENTIAL RESISTANCE $r_{dif}(\Omega)$ at $I_{Ztest}$		IP. COI z (mV/I at I <sub>ztest</sub> Figs 4 a	<b>&lt;</b> )	TEST CURRENT I <sub>Ztest</sub> (mA)	DIODE CAP. $C_{d} (pF)$ at f = 1 MHz; at $V_{R} = 0 V$	REVER CURREI REVER VOLTA	NT at RSE	NON-REPETITIVE PEAK REVERSE CURRENT I <sub>ZSM</sub> (A) at t <sub>p</sub> = 100 μs;
										<b>I</b> <sub>R</sub> (μ <b>A</b> )	V <sub>R</sub>	T <sub>amb</sub> = 25 °C
	MIN.	MAX.	TYP.	MAX.	MIN.	TYP.	MAX.		MAX.	MAX.	(V)	MAX.
2V4	2.2	2.6	70	100	-3.5	-1.6	0	5	450	50	1.0	6.0
2V7	2.5	2.9	75	100	-3.5	-2.0	0	5	450	20	1.0	6.0
3V0	2.8	3.2	80	95	-3.5	-2.1	0	5	450	10	1.0	6.0
3V3	3.1	3.5	85	95	-3.5	-2.4	0	5	450	5	1.0	6.0
3V6	3.4	3.8	85	90	-3.5	-2.4	0	5	450	5	1.0	6.0
3V9	3.7	4.1	85	90	-3.5	-2.5	0	5	450	3	1.0	6.0
4V3	4.0	4.6	80	90	-3.5	-2.5	0	5	450	3	1.0	6.0
4V7	4.4	5.0	50	80	-3.5	-1.4	+0.2	5	300	3	2.0	6.0
5V1	4.8	5.4	40	60	-2.7	-0.8	+1.2	5	300	2	2.0	6.0
5V6	5.2	6.0	15	40	-2.0	+1.2	+2.5	5	300	1	2.0	6.0
6V2	5.8	6.6	6	10	0.4	2.3	3.7	5	200	3	4.0	6.0
6V8	6.4	7.2	6	15	1.2	3.0	4.5	5	200	2	4.0	6.0
7V5	7.0	7.9	6	15	2.5	4.0	5.3	5	150	1	5.0	4.0
8V2	7.7	8.7	6	15	3.2	4.6	6.2	5	150	0.7	5.0	4.0
9V1	8.5	9.6	6	15	3.8	5.5	7.0	5	150	0.5	6.0	3.0
10	9.4	10.6	8	20	4.5	6.4	8.0	5	90	0.2	7.0	3.0
11	10.4	11.6	10	20	5.4	7.4	9.0	5	85	0.1	8.0	2.5
12	11.4	12.7	10	25	6.0	8.4	10.0	5	85	0.1	8.0	2.5
13	12.4	14.1	10	30	7.0	9.4	11.0	5	80	0.1	8.0	2.5
15	13.8	15.6	10	30	9.2	11.4	13.0	5	75	0.05	10.5	2.0
16	15.3	17.1	10	40	10.4	12.4	14.0	5	75	0.05	11.2	1.5
18	16.8	19.1	10	45	12.4	14.4	16.0	5	70	0.05	12.6	1.5
20	18.8	21.2	15	55	14.4	16.4	18.0	5	60	0.05	14.0	1.5
22	20.8	23.3	20	55	16.4	18.4	20.0	5	60	0.05	15.4	1.25
24	22.8	25.6	25	70	18.4	20.4	22.0	5	55	0.05	16.8	1.25

Product data sheet

BZV49- CXXX	VOL <sup>T</sup>	KING FAGE (V) Ztest	DIFFERENTIAL RESISTANCE $r_{dif}\left(\Omega\right)$ at $I_{Ztest}$		TEMP. COEFF. S <sub>Z</sub> (mV/K) at I <sub>Ztest</sub> see Figs 4 and 5		TEST CURRENT I <sub>Ztest</sub> (mA)	DIODE CAP. $C_d$ (pF) at f = 1 MHz; at $V_R$ = 0 V	REVER CURREI REVER VOLTA	NT at RSE	NON-REPETITIVE PEAK REVERSE CURRENT  I <sub>ZSM</sub> (A)  at t <sub>p</sub> = 100 μs;  T <sub>amb</sub> = 25 °C	
	MIN.	MAX.	TYP.	MAX.	MIN.	TYP.	MAX.		MAX.	MAX.	(V)	MAX.
27	25.1	28.9	25	80	21.4	23.4	25.3	2	50	0.05	18.9	1.0
30	28.0	32.0	30	80	24.4	26.6	29.4	2	50	0.05	21.0	1.0
33	31.0	35.0	35	80	27.4	29.7	33.4	2	45	0.05	23.1	0.9
36	34.0	38.0	35	90	30.4	33.0	37.4	2	45	0.05	25.2	0.8
39	37.0	41.0	40	130	33.4	36.4	41.2	2	45	0.05	27.3	0.7
43	40.0	46.0	45	150	37.6	41.2	46.6	2	40	0.05	30.1	0.6
47	44.0	50.0	50	170	42.0	46.1	51.8	2	40	0.05	32.9	0.5
51	48.0	54.0	60	180	46.6	51.0	57.2	2	40	0.05	35.7	0.4
56	52.0	60.0	70	200	52.2	57.0	63.8	2	40	0.05	39.2	0.3
62	58.0	66.0	80	215	58.8	64.4	71.6	2	35	0.05	43.4	0.3
68	64.0	72.0	90	240	65.6	71.7	79.8	2	35	0.05	47.6	0.25
75	70.0	79.0	95	255	73.4	80.2	88.6	2	35	0.05	52.5	0.2

# Voltage regulator diodes

BZV49 series

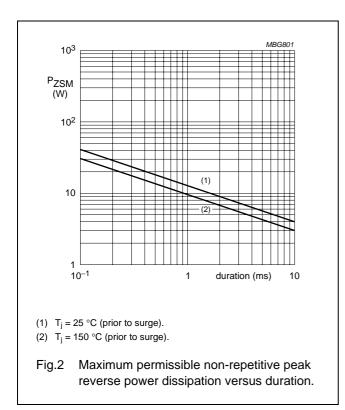
#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-tp)</sub>	thermal resistance from junction to tie-point		15	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	125	K/W

#### Note

1. Device mounted on a ceramic substrate; area = 2.5 cm<sup>2</sup>; thickness = 0.7 mm.

#### **GRAPHICAL DATA**



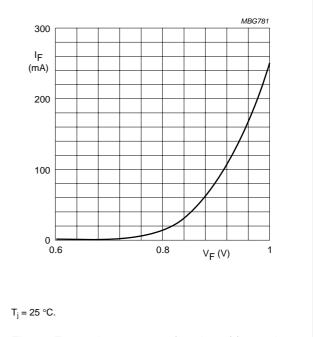
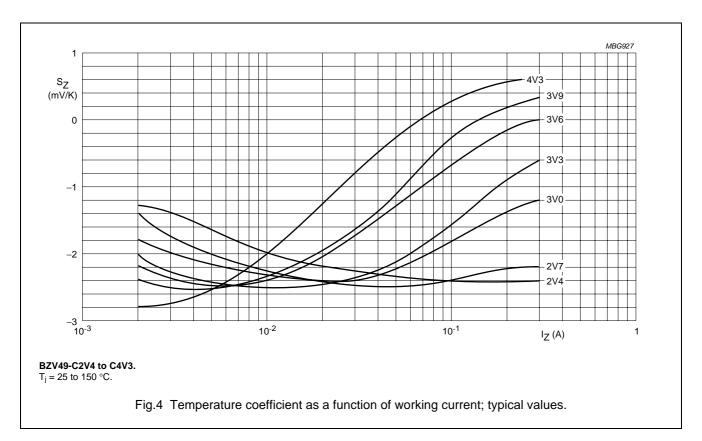
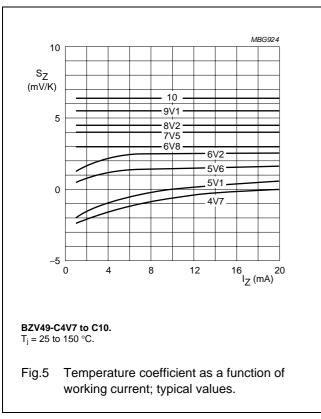


Fig.3 Forward current as a function of forward voltage; typical values.

# Voltage regulator diodes

# BZV49 series





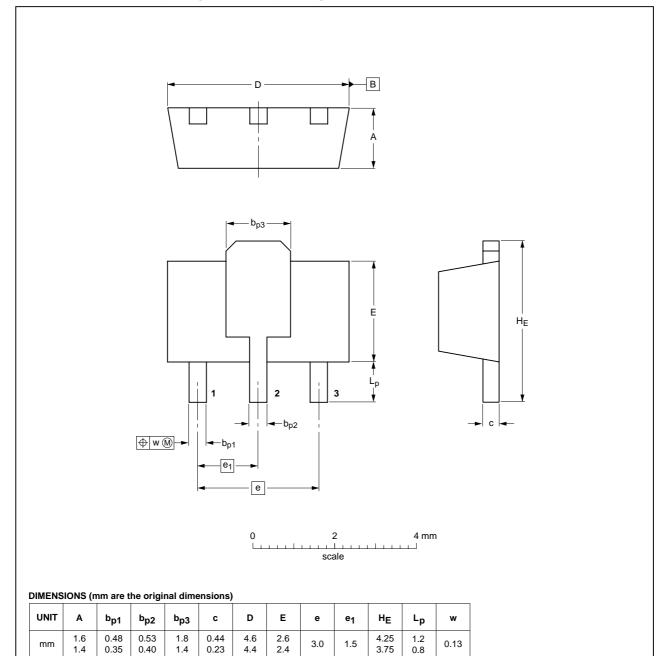
# Voltage regulator diodes

BZV49 series

#### **PACKAGE OUTLINE**

#### Plastic surface-mounted package; collector pad for good heat transfer; 3 leads

SOT89



OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE	
SOT89		TO-243	SC-62		<del>04-08-03</del> 06-03-16	

### Voltage regulator diodes

BZV49 series

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

For additional information please visit: http://www.nxp.com
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